

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A semiconductor device module comprising:

a semiconductor device including:

a multi-layer wiring board ~~which comprises insulation layers and circuit pattern layers laminated alternately and is provided with a three-dimensional wiring comprising said circuit pattern layers provided on both sides of the insulation layer and a plurality of inner via holes penetrating through each of said insulation layers and electrically connecting~~ having a first side and a second side, said multi-layer wiring board including a plurality of insulation layers each having a first side and a second side, and including a plurality of circuit pattern layers arranged such that one of said circuit pattern layers is located on each of said first side and said second side of each of said insulation layers, said insulation layers and said circuit pattern layers being alternately laminated, and wherein each of said insulation layers has a plurality of inner via holes extending between said first side and said second side of said each of said insulation layers and electrically connecting said circuit pattern layers so as to define a three-dimensional wiring pattern; and

at least a first semiconductor element mounted on ~~the one~~ said first side of the said multi-layer wiring board and a second semiconductor element mounted ~~on the other~~ said second side of said multi-layer wiring board wherein electrodes of said first semiconductor element and said second semiconductor element ~~elements~~ are connected with each other by ~~means of~~ said three-dimensional wiring pattern of said multi-layer wiring board; and

a mother multi-layer wiring board having a circuit pattern formed on ~~said a~~ a surface thereof, wherein said semiconductor device is mounted on said mother multi-layer wiring board and said semiconductor device and said mother multi-layer wiring board are electrically ~~connected by electrical connection means.~~

2. (Currently Amended) The ~~module of the~~ semiconductor device module according to claim 1, wherein said ~~electrical connection means is~~ said semiconductor device and said mother multi-

layer wiring board are electrically connected by a projecting electrode which is interposed between said multi-layer wiring board of said semiconductor device and said mother multi-layer wiring board by bonding said back surface of said second semiconductor element onto said mother multi-layer wiring board thus placing said semiconductor device on said mother multi-layer wiring board, thereby ~~to connect~~ connecting said circuit pattern provided on said multi-layer wiring board and said circuit pattern provided on said mother multi-layer wiring board.

3. (Currently Amended) The ~~module of the~~ semiconductor device module according to claim 1, wherein said ~~electrical connection means is~~ said semiconductor device and said mother multi-layer wiring board are electrically connected by an electrically conductive supporting body which is electrically connected to said three-dimensional wiring pattern in of said multi-layer wiring board of said semiconductor device and which is also used to fasten ~~fastens~~ said semiconductor device onto said mother multi-layer wiring board, so as to establish electrical connection between said three-dimensional wiring pattern of said multi-layer wiring board of said semiconductor device and said circuit pattern provided on said mother multi-layer wiring board by fastening said semiconductor device onto said mother multi-layer wiring board via said electrically conductive supporting body.